IR-Lumineszenzdiode
Infrared Emitter
Lead (Pb) Free Product - RoHS Compliant

LD 271
LD 271 H
LD 271 L
LD 271 LH

Wesentliche Merkmale

- GaAs-LED in 5mm radial-Gehäuse
- Typische Peakwellenlänge 950nm
- Hohe Zuverlässigkeit
- Mit verschiedenen Beinchenlängen lieferbar
- Variante mit “stand-off” lieferbar
- TTW Löten geeignet

Features

- GaAs-LED in 5mm radial package (T 1 $^3/_4$)
- Typical peak wavelength 950nm
- High reliability
- Available with two different lead lengths
- Version with stand-off available
- Suitable for TTW soldering

Anwendungen

- IR-Fernsteuerung von Fernseh- und Rundfunkgeräten, Videorecordern, Lichtdimmern
- Gerätefernsteuerungen für Gleich- und Wechsellichtbetrieb
- Sensorik
- Diskrete Lichtschranken

Applications

- IR remote control of hi-fi and TV-sets, video tape recorders, dimmers
- Remote control for steady and varying intensity
- Sensor technology
- Discrete interrupters

Typ **Type**	**Bestellnummer** **Ordering Code**	**Strahlstärkegruppierung** [1] (I_F = 100mA, t_p = 20 ms) **Radiant intensity grouping** [1] I_e (mW/sr)
LD 271	Q62703Q0148	15 (>10)
LD 271 L	Q62703Q0833	
LD 271 H	Q62703Q0256	>16
LD 271 LH	Q62703Q0838	

[1] gemessen bei einem Raumwinkel Ω = 0.01 sr
measured at a solid angle of Ω = 0.01 sr

Opto Semiconductors OSRAM

Grenzwerte
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	T_{op}; T_{stg}	– 40 … + 100	°C
Sperrspannung Reverse voltage	V_R	5	V
Durchlaßstrom Forward current	I_F	130	mA
Stoßstrom, t_p = 10 µs, D = 0 Surge current	I_{FSM}	3.5	A
Verlustleistung Power dissipation	P_{tot}	220	mW
Wärmewiderstand Thermal resistance	R_{thJA}	330	K/W

Kennwerte (T_A = 25 °C)
Characteristics

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength at peak emission I_F = 100 mA, t_p = 20 ms	λ_{peak}	950	nm
Spektrale Bandbreite bei 50% von I_{max} Spectral bandwidth at 50% of I_{max} I_F = 100 mA	$\Delta\lambda$	55	nm
Abstrahlwinkel Half angle	φ	± 25	Grad deg.
Aktive Chipfläche Active chip area	A	0.25	mm^2
Abmessungen der aktiven Chipfläche Dimensions of the active chip area	$L \times B$ $L \times W$	0.5 × 0.5	mm²
Abstand Chipoberfläche bis Linsenscheitel Distance chip front to lens top	H	4.0 … 4.6	mm
Schaltzeiten, I_e von 10% auf 90% und von 90% auf 10%, bei I_F = 100 mA, R_L = 50 Ω Switching times, I_e from 10% to 90% and from 90% to 10%, I_F = 100 mA, R_L = 50 Ω	t_r, t_f	1	µs

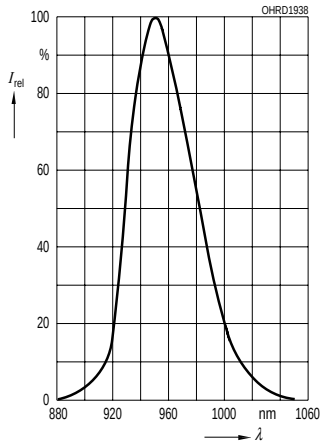
Kennwerte (T_A = 25 °C)
Characteristics (cont'd)

Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**	**Einheit** **Unit**
Kapazität, V_R = 0 V, f = 1 MHz Capacitance	C_o	40	pF
Durchlaßspannung Forward voltage I_F = 100 mA, t_p = 20 ms I_F = 1 A, t_p = 100 µs	 V_F V_F	 1.30 (≤ 1.5) 1.90 (≤ 2.5)	 V V
Sperrstrom, V_R = 5 V Reverse current	I_R	0.01 (≤ 1)	µA
Gesamtstrahlungsfluß Total radiant flux I_F = 100 mA, t_p = 20 ms	Φ_e	18	mW
Temperaturkoeffizient von I_e bzw. Φ_e, I_F = 100 mA Temperature coefficient of I_e or Φ_e, I_F = 100 mA	TC_I	– 0.55	%/K
Temperaturkoeffizient von V_F, I_F = 100 mA Temperature coefficient of V_F, I_F = 100 mA	TC_V	– 1.5	mV/K
Temperaturkoeffizient von λ, I_F = 100 mA Temperature coefficient of λ, I_F = 100 mA	TC_λ	0.3	nm/K

Gruppierung der Strahlstärke I_e in Achsrichtung
gemessen bei einem Raumwinkel Ω = 0.01 sr
Grouping of Radiant Intensity I_e in Axial Direction
at a solid angle of Ω = 0.01 sr

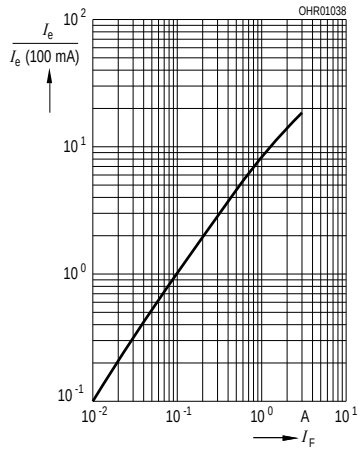
Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**		**Einheit** **Unit**
		LD 271 **LD 271 L**	**LD 271 H** **LD 271 LH**	
Strahlstärke Radiant intensity I_F = 100 mA, t_p = 20 ms I_F = 1 A, t_p = 100 µs	 I_e $I_{e\ typ.}$	 15 (> 10) 120	 > 16	 mW/sr mW/sr

Relative Spectral emission
$I_{rel} = f(\lambda)$

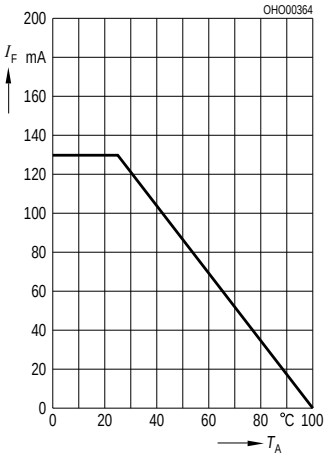


Radiant Intensity $\frac{I_e}{I_e\ 100\ mA} = f(I_F)$

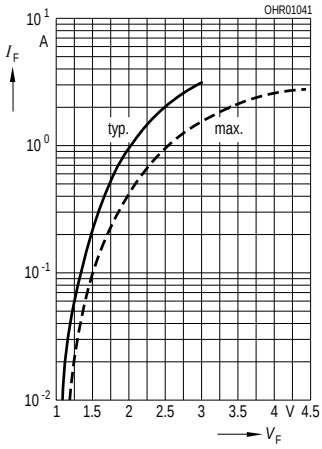
Single pulse, t_p = 20 µs



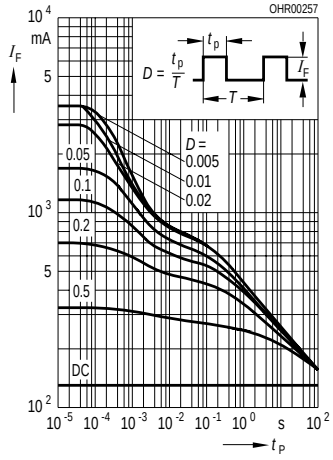
Max. Permissible Forward Current
$I_F = f(T_A)$



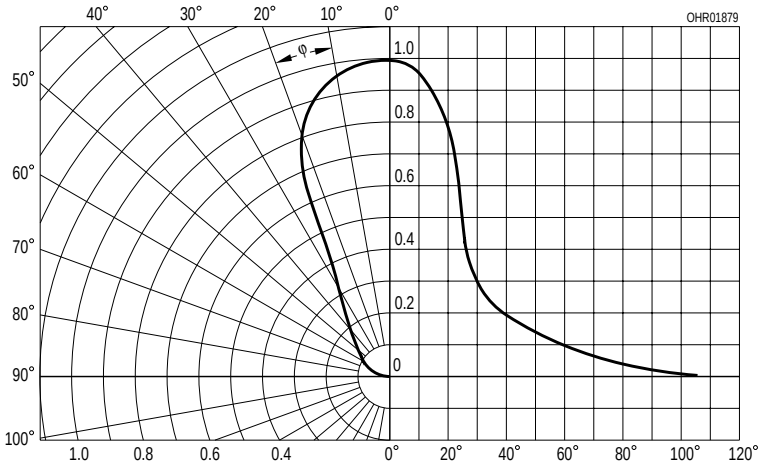
Forward Current
$I_F = f(V_F)$, single pulse, t_p = 20 µs



Permissible Pulse Handling Capability $I_F = f(\tau)$, T_C = 25 °C, duty cycle D = parameter

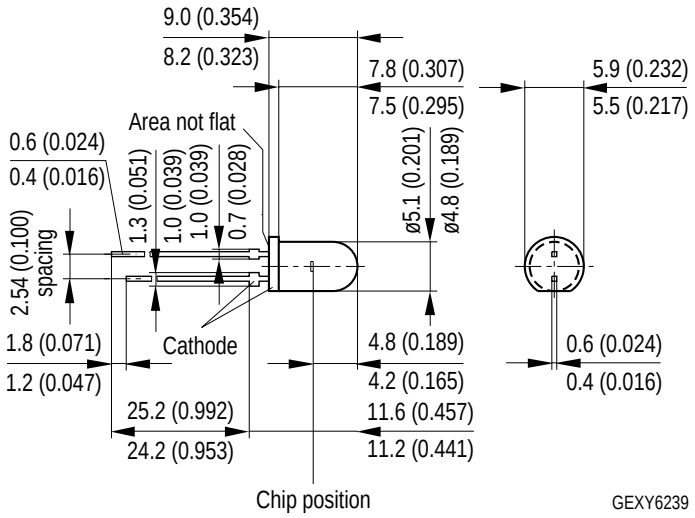


Radiation Characteristics $I_{rel} = f(\varphi)$

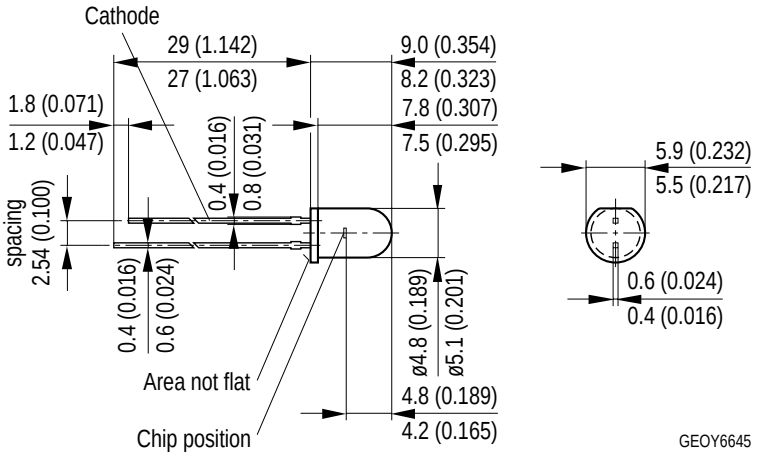


Maßzeichnung
Package Outlines

LD 271 / LD 271 H



LD 271 L / LD 271 LH



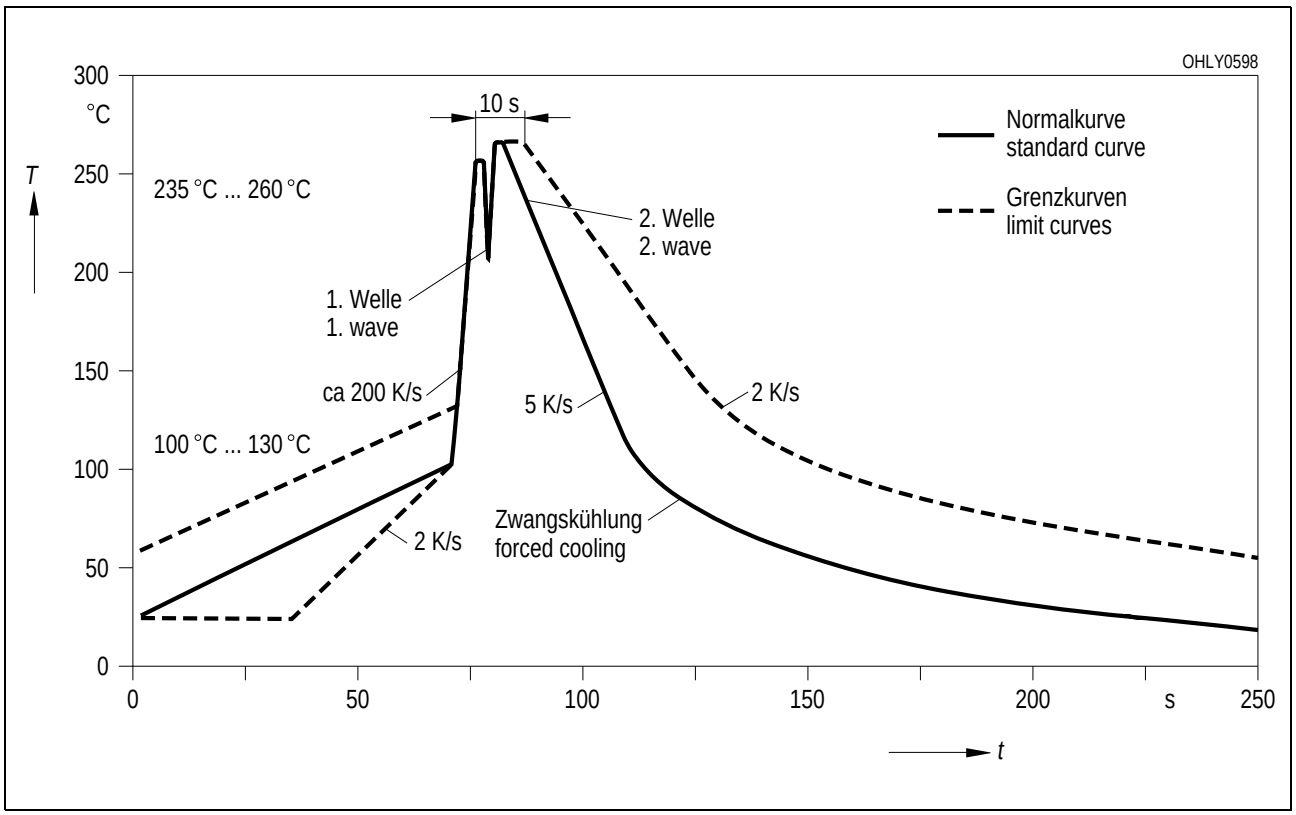
Maße in mm (inch) / Dimensions in mm (inch).

Gehäusefarbe: grau
Brechungsindex Verguss: 1.53

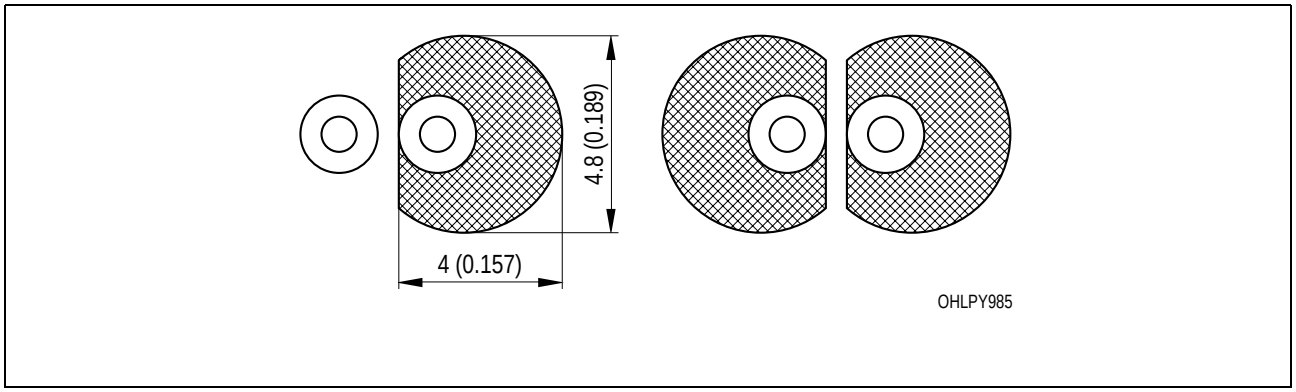
Package Colour: grey
Refractive index resin: 1.53

Lötbedingungen
Soldering Conditions

Wellenlöten (TTW) (nach CECC 00802)
TTW Soldering (acc. to CECC 00802)



Empfohlenes Lötpaddesign Wellenlöten (TTW)
Recommended Solder Pad TTW Soldering



Maße in mm (inch) / Dimensions in mm (inch).

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EU RoHS and China RoHS compliant product

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